



SETTING STANDARDS
IN POWER SOLUTIONS

Declaration of RoHS Compliance

Product Description: Secondary Lithium Ion batteries

Model Number: RRC2020y

Assembly Number: 100496-xx, 110102-xx, 110270-xx, 110132-xx, 110194-xx

RRC Power Solutions declares that to its knowledge, as of the date of this document, the products listed above conform to the requirements of the European Union's Restriction of Hazardous Substances (RoHS) Directive 2011/65/EU including Directive (EU) 2015/863 which amended RoHS to add 4 phthalates.

At RRC Power Solutions, the term RoHS Compliant indicates that named products are compliant with the RoHS requirement that the ten restricted substances are present below the specified maximum concentration value by weight in homogeneous materials (see table below). Some RoHS Compliant products may contain restricted substances in applications for which exemptions have been granted by the RoHS Directive. Any known exemptions are listed below.

Restricted Substance	Maximum Concentration Value (%)
Cadmium (Cd)	0.01%
Lead (Pb)	0.1%
Mercury (Hg)	0.1%
Hexavalent Chromium (Cr(VI))	0.1%
Polybrominated biphenyls (PBB)	0.1%
Polybrominated diphenylethers (PBDE)	0.1%
Bis(2-ethylhexyl) phthalate (DEHP)	0.1%
Butyl benzyl phthalate (BBP)	0.1%
Dibutyl phthalate (DBP)	0.1%
Diisobutyl phthalate (DIBP)	0.1%

RoHS Exemptions	
Exemption List EL2011/534/EU	Authority IPC
Exemption ID	Description
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

This declaration is based on RRC Power Solutions understanding of the requirements of the RoHS Directive and knowledge of the materials that go into its products. RRC Power Solutions bases its knowledge on information provided by third-party suppliers and makes no representation or warranty as to the accuracy of such information. RRC Power Solutions continues to take steps to obtain accurate information from suppliers but has not conducted destructive testing or chemical analysis on incoming materials to verify material composition.

Date Issued:

08-Sep-23

RRC Power Solutions

Technologiepark 1 -

Homburg, Saar 66424

Germany

Authorized Signature:

Steven Diehl, Chief Technology Officer

Declaration of REACH Compliance

Product Description: Secondary Lithium Ion batteries

Model Number: RRC2020y

Assembly Number: 100496-xx, 110102-xx, 110270-xx, 110132-xx, 110194-xx

RRC Power Solutions declares that, to its knowledge as of the date of this document, the products listed above do contain one or more of the 233 Substances of Very High Concern (SVHCs) listed in the January 17, 2023 Candidate List of the REACH Regulation EC 1907/2006. REACH SVHCs which are not found on the Authorization List are not restricted but must be declared in accordance with REACH Article 33. Based on the information available, the products contain the following SVHC(s):

Substance	CAS	EC
Lead	7439-92-1	231-100-4

This declaration is based on RRC Power Solutions's understanding of the requirements of the REACH Regulation and knowledge of the materials that go into its products. RRC Power Solutions bases its knowledge on information provided by third-party suppliers and makes no representation or warranty as to the accuracy of such information. RRC Power Solutions continues to take steps to obtain accurate information from suppliers but has not conducted destructive testing or chemical analysis on incoming materials to verify material composition.

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Homburg, 66424

Germany

Authorized Signature:



Steven Diehl, Chief Technology Officer



Material Composition Declaration

This document is a declaration of the substances within the manufacturer listed item. Note: If the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

See IPC Web Site for Information on IPC-1750 Series Standard

<http://www.ipc.org/ContentPage.aspx?pageid=Materials-Declaration>

Form Type
Distribute

Version
2.0

Supplier Information

Company Name RRC Power Solutions								
Company Unique ID		Unique ID Authority		Supplier Contact		Authorized Representative		
Response Date 2023-09-08		Response Document ID		Name		Name		
Supplier Comments				Title		Title		
				Phone		Phone		
				Email		Email		
	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight & UOM	Unit Type
	100496-xx, 110102-xx, 110270-xx, 110132-xx, 110194-xx	100496-xx, 110102-xx, 110270-xx, 110132-xx, 110194-xx	RRC2020y	2023-09-01			818.3185 mg	Each

Legal Statement

Legal Declaration Standard	Supplier Acceptance Accepted
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Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Supplier Digital Signature

Instructions: Place the digital signature in the space provided here.

RoHS Exemptions

Exemption List EL2011/534/EU		Authority IPC
Exemption ID	Description	
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)	
7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound	

Query List

Query	Statement	Response
EUROHS-1907	Product(s) meets EU RoHS requirements by application of the selected exemption(s)	True
EUREACH-0123	Product(s) does not contain EU REACH Candidate List substances above the thresholds specified in the REACH Regulation	False

Homogeneous Materials

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
203204	8.3955 mg	Lead Frame_Copper Alloy	0.3208 mg	Copper and its alloys	Copper	7440-50-8		0.3112 mg	97 %
				Metal	Iron	7439-89-6		0.0096 mg	3 %
		Lead Frame Plating_Matte Tin	0.0294 mg	Lead/Lead Compounds	Lead	7439-92-1		0 mg	0.0987 %
				Metal	Tin	7440-31-5		0.0294 mg	99.9013 %
		Bond Wire_Copper	0.01 mg	Copper and its alloys	Copper	7440-50-8		0.01 mg	100 %
		Dice_Silicon	0.0578 mg	Aluminum and its alloys	Aluminum	7429-90-5		0.0001 mg	0.163 %
				Copper and its alloys	Copper	7440-50-8		0 mg	0.001 %
				Metalloid	Silicon	7440-21-3		0.0576 mg	99.726 %
		Mold Compound_Epoxy with Silica Filler	7.9775 mg	Metal	Tungsten	7440-33-7		0.0001 mg	0.11 %
				Chemical	Carbon Black	1333-86-4		0.0399 mg	0.5003 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		0.2395 mg	3.0017 %
				Chemical	Epoxy Resin			0.5987 mg	7.5042 %
				Chemical	Phenolic Resin			0.235 mg	2.9453 %
				Chemical	Silica	7631-86-9		0.2395 mg	3.0017 %
				Chemical	Silica Fused	60676-86-0		6.6251 mg	83.0468 %
203204	8.02 mg	Mold Compound_Epoxy with Silica Filler	4.9 mg	Chemical	1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, compd. with 1,3,5-triazine-2,4,6-triamine (1:1)	37640-57-6		0.147 mg	3 %
				Chemical	Carbon Black	1333-86-4		0.049 mg	1 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		0.392 mg	8 %
				Chemical	Phenolic Novolac	9003-35-4		0.2205 mg	4.5 %
				Chemical	Silica	7631-86-9		3.92 mg	80 %
				Chemical	Zinc Borate 2335	138265-88-0		0.147 mg	3 %
		Lead Frame_Metal Alloy	2.92 mg	Oxide	Zinc oxide	1314-13-2		0.0245 mg	0.5 %
				Copper and its alloys	Copper	7440-50-8		0.3942 mg	13.5 %
				Metal	Iron	7439-89-6		1.4658 mg	50.2 %
		Plating_Matte Tin	0.14 mg	Nickel/Nickel Compounds	Nickel	7440-02-0		1.06 mg	36.3 %
				Metal	Tin	7440-31-5		0.14 mg	100 %
				Die_Doped Silicon	Silicon	7440-21-3		0.05 mg	100 %
				Bond Wire_Copper	Copper	7440-50-8		0.01 mg	100 %
203204	9.325 mg	Chip_Doped Silicon	0.101 mg	Precious metals	Gold	7440-57-5		0.008 mg	7.9208 %
				Metalloid	Silicon	7440-21-3		0.091 mg	90.099 %
				Metal	Tin	7440-31-5		0.002 mg	1.9802 %
		Lead Frame_Copper Alloy	3.013 mg	Metal	Chromium	7440-47-3		0.009 mg	0.2987 %
				Copper and its alloys	Copper	7440-50-8		3 mg	99.5685 %
				Metalloid	Silicon	7440-21-3		0.001 mg	0.0332 %
				Metal	Titanium	7440-32-6		0.003 mg	0.0996 %
		Wire_Copper	0.008 mg	Copper and its alloys	Copper	7440-50-8		0.008 mg	100 %
		Encapsulation_Epoxy with Silica Filler	5.769 mg	Chemical	Carbon Black	1333-86-4		0.058 mg	1.0054 %
				Chemical	Epoxy Resin			1.24 mg	21.4942 %
				Chemical	Silica Fused	60676-86-0		4.471 mg	77.5004 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
206116	1.106 mg	Lead Finish_Matte Tin	0.15 mg	Metal	Tin	7440-31-5		0.15 mg	100 %
		Plating_Silver	0.284 mg	Metal	Silver	7440-22-4		0.284 mg	100 %
		Chip_Crystal	0.047 mg	Aluminum and its alloys	Aluminum	7429-90-5		0.0001 mg	0.286 %
				Metal	Chromium	7440-47-3		0 mg	0.003 %
				Chemical	diindium trioxide	1312-43-2		0.0001 mg	0.286 %
				Chemical	Gallium	7440-55-3		0.0008 mg	1.65 %
				ANNEX XVII of REACH Regulation (EC) No 1907/2006 and Commission Regulation (EU) No 1272/2013	Gallium arsenide	1303-00-0		0.0447 mg	95.143 %
				Precious metals	Gold	7440-57-5		0.0003 mg	0.585 %
				Oxide	Indium tin oxide	50926-11-9		0.0001 mg	0.189 %
				Chemical	Phosphorus	7723-14-0		0.0009 mg	1.858 %
		Epoxy_Epoxy, Silver Filled	0.032 mg	Chemical	Adhesive			0.0016 mg	5 %
				Chemical	Cresyl glycidyl ether	26447-14-3		0.0016 mg	5 %
				Chemical	Dicyandiamide	461-58-5		0.0003 mg	1 %
				Chemical	Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5		0.0016 mg	5 %
				Chemical	Phenolic Resin			0.0016 mg	5 %
				Metal	Silver	7440-22-4		0.0253 mg	79 %
				PCB_Glass and Metal	Barium	7440-39-3		0.0066 mg	1.9 %
				Copper and its alloys	Copper	7440-50-8		0.099 mg	28.3 %
				Ceramics / Glass	Fiberglass	65997-17-3		0.1792 mg	51.2 %
				Precious metals	Gold	7440-57-5		0.0014 mg	0.4 %
				Chemical	Heavy aromatic naphtha solvent	64742-94-5		0.0042 mg	1.2 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.0199 mg	5.7 %
				Chemical	Silica	7631-86-9		0.0039 mg	1.1 %
				Oxide	Silicon dioxide	14808-60-7		0.0203 mg	5.8 %
				Metal	Silver	7440-22-4		0.0126 mg	3.6 %
				Chemical	Tridymite	15468-32-3		0.0028 mg	0.8 %
		Wire_Gold	0.085 mg	Precious metals	Gold	7440-57-5		0.085 mg	100 %
		Compound_Epoxy	0.592 mg	Chemical	2,6-di-tert-butyl-p-cresol	128-37-0		0.0059 mg	1 %
206116	1.106 mg	Chip_Crystal	0.047 mg	Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.4322 mg	73 %
				Phthalates	Tetrahydrophthalic anhydride	85-43-8		0.1539 mg	26 %
				Aluminum and its alloys	Aluminum	7429-90-5		0.0001 mg	0.286 %
				Metal	Chromium	7440-47-3		0 mg	0.003 %
				Chemical	diindium trioxide	1312-43-2		0.0001 mg	0.286 %
				Chemical	Gallium	7440-55-3		0.0008 mg	1.65 %
				ANNEX XVII of REACH Regulation (EC) No 1907/2006 and Commission Regulation (EU) No 1272/2013	Gallium arsenide	1303-00-0		0.0447 mg	95.143 %
				Precious metals	Gold	7440-57-5		0.0003 mg	0.585 %
				Oxide	Indium tin oxide	50926-11-9		0.0001 mg	0.189 %
				Chemical	Phosphorus	7723-14-0		0.0009 mg	1.858 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
		Epoxy_Epoxy, Silver Filled	0.032 mg	Chemical	Adhesive			0.0016 mg	5 %
				Chemical	Cresyl glycidyl ether	26447-14-3		0.0016 mg	5 %
				Chemical	Dicyandiamide	461-58-5		0.0003 mg	1 %
				Chemical	Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5		0.0016 mg	5 %
				Chemical	Phenolic Resin			0.0016 mg	5 %
				Metal	Silver	7440-22-4		0.0253 mg	79 %
	PCB_Glass and Metal		0.35 mg	Metal	Barium	7440-39-3		0.0066 mg	1.9 %
				Copper and its alloys	Copper	7440-50-8		0.099 mg	28.3 %
				Ceramics / Glass	Fiberglass	65997-17-3		0.1792 mg	51.2 %
				Precious metals	Gold	7440-57-5		0.0014 mg	0.4 %
				Chemical	Heavy aromatic naphtha solvent	64742-94-5		0.0042 mg	1.2 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.0199 mg	5.7 %
				Chemical	Silica	7631-86-9		0.0039 mg	1.1 %
				Oxide	Silicon dioxide	14808-60-7		0.0203 mg	5.8 %
				Metal	Silver	7440-22-4		0.0126 mg	3.6 %
				Chemical	Tridymite	15468-32-3		0.0028 mg	0.8 %
	Wire_Gold		0.085 mg	Precious metals	Gold	7440-57-5		0.085 mg	100 %
	Compound_Epoxy		0.592 mg	Chemical	2,6-di-tert-butyl-p-cresol	128-37-0		0.0059 mg	1 %
				Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.4322 mg	73 %
				Phthalates	Tetrahydropthalic anhydride	85-43-8		0.1539 mg	26 %
206116	1.106 mg	Chip_Crystal	0.047 mg	Aluminum and its alloys	Aluminum	7429-90-5		0.0001 mg	0.286 %
				Metal	Chromium	7440-47-3		0 mg	0.003 %
				Chemical	diindium trioxide	1312-43-2		0.0001 mg	0.286 %
				Chemical	Gallium	7440-55-3		0.0008 mg	1.65 %
				ANNEX XVII of REACH Regulation (EC) No 1907/2006 and Commission Regulation (EU) No 1272/2013	Gallium arsenide	1303-00-0		0.0447 mg	95.143 %
				Precious metals	Gold	7440-57-5		0.0003 mg	0.585 %
				Oxide	Indium tin oxide	50926-11-9		0.0001 mg	0.189 %
				Chemical	Phosphorus	7723-14-0		0.0009 mg	1.858 %
	Epoxy_Epoxy, Silver Filled		0.032 mg	Chemical	Adhesive			0.0016 mg	5 %
				Chemical	Cresyl glycidyl ether	26447-14-3		0.0016 mg	5 %
				Chemical	Dicyandiamide	461-58-5		0.0003 mg	1 %
				Chemical	Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5		0.0016 mg	5 %
				Chemical	Phenolic Resin			0.0016 mg	5 %
				Metal	Silver	7440-22-4		0.0253 mg	79 %
	PCB_Glass and Metal		0.35 mg	Metal	Barium	7440-39-3		0.0066 mg	1.9 %
				Copper and its alloys	Copper	7440-50-8		0.099 mg	28.3 %
				Ceramics / Glass	Fiberglass	65997-17-3		0.1792 mg	51.2 %
				Precious metals	Gold	7440-57-5		0.0014 mg	0.4 %
				Chemical	Heavy aromatic naphtha solvent	64742-94-5		0.0042 mg	1.2 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration		
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.0199 mg	5.7 %		
				Chemical	Silica	7631-86-9		0.0039 mg	1.1 %		
				Oxide	Silicon dioxide	14808-60-7		0.0203 mg	5.8 %		
				Metal	Silver	7440-22-4		0.0126 mg	3.6 %		
				Chemical	Tridymite	15468-32-3		0.0028 mg	0.8 %		
		Wire_Gold	0.085 mg	Precious metals	Gold	7440-57-5		0.085 mg	100 %		
		Compound_Epoxy	0.592 mg	Chemical	2,6-di-tert-butyl-p-cresol	128-37-0		0.0059 mg	1 %		
				Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.4322 mg	73 %		
				Phthalates	Tetrahydrophthalic anhydride	85-43-8		0.1539 mg	26 %		
206287	8.5057 mg	Substrate_Ceramic	7.6146 mg	Ceramics / Glass	Alumina	1344-28-1		7.31 mg	96.0001 %		
				Oxide	Magnesium Oxide	1309-48-4		0.1523 mg	2 %		
				Chemical	Silica	7631-86-9		0.1523 mg	2 %		
				Inner Electrode_Glass and Metal	0.038 mg	Metal	Palladium	7440-05-3		0.0005 mg	1.4196 %
						Metal	Silver	7440-22-4		0.0375 mg	98.5804 %
		Inner Electrode_Silver	0.0194 mg	Metal	Silver	7440-22-4		0.0194 mg	100 %		
		Resistive Layer_Glass and Metal	0.0436 mg	Lead/Lead Compounds	Frits, Chemicals (Leaded)	65997-18-4	7(c)-I	0.0018 mg	4.0092 %		
				Oxide	Ruthenium dioxide	12036-10-1		0.0332 mg	75.9908 %		
				Metal	Silver	7440-22-4		0.0087 mg	20 %		
				Plating_Nickel Barrier	0.2444 mg	Nickel/Nickel Compounds	Nickel	7440-02-0		0.2444 mg	100 %
		Plating_Matte Tin	0.2108 mg	Metal	Tin	7440-31-5		0.2108 mg	100 %		
		Primary glass_Glass	0.0635 mg	Bismuth/Bismuth Compounds	Bismuth trioxide	1304-76-3		0.0489 mg	77.0043 %		
				Metalloid	Boron	7440-42-8		0.0051 mg	8.0013 %		
				Chemical	Silica Fused	60676-86-0		0.0095 mg	14.9945 %		
				Overcoat_Epoxy Resin	0.2698 mg	Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.054 mg	20.0007 %
						Chemical	C.I. Pigment Black 28	68186-91-4		0.2159 mg	79.9993 %
		Marking_Epoxy Resin	0.0014 mg	Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.0014 mg	100 %		
206287	8.484 mg	Substrate_Ceramic	8.0655 mg	Ceramics / Glass	Alumina	1344-28-1		7.7211 mg	95.7301 %		
				Oxide	Calcium oxide	1305-78-8		0.1484 mg	1.8398 %		
				Oxide	Magnesium Oxide	1309-48-4		0.0476 mg	0.5903 %		
				Oxide	Silicon dioxide	14808-60-7		0.1484 mg	1.8398 %		
				Backside Layer_Paste	0.0176 mg	Chemical	Ethylcellulose	9004-57-3		0.0018 mg	10.0228 %
				Chemical	Frits, chemicals (Pb-free)	65997-18-4		0.0019 mg	10.9909 %		
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.001 mg	5.9795 %		
				Metal	Silver	7440-22-4		0.0128 mg	73.0068 %		
				Topside Layer_Paste	0.1142 mg	Chemical	Ethylcellulose	9004-57-3			
				Chemical	Frits, chemicals (Pb-free)	65997-18-4		0.0138 mg	12.1148 %		
				Metal	Palladium	7440-05-3		0.0007 mg	0.6303 %		
				Metal	Silver	7440-22-4		0.0997 mg	87.2549 %		
				Resistive Layer_Glass and Metal	0.0452 mg	Chemical	Frits, chemicals (Pb-free)	65997-18-4		0.003 mg	6.6667 %
				Lead/Lead Compounds	Lead (II) Oxide	1317-36-8	7(c)-I	0.0075 mg	16.6556 %		
				Metal	Palladium	7440-05-3		0.006 mg	13.3333 %		
				Oxide	Ruthenium dioxide	12036-10-1		0.0023 mg	5.0055 %		

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
206414	1.1493 mg	Primary Coating_Coating	0.0602 mg	Chemical	Silica	7631-86-9		0.0113 mg	25.0055 %
				Metal	Silver	7440-22-4		0.015 mg	33.3333 %
				Oxide	Chromium Oxide	1308-38-9		0.0004 mg	0.6978 %
				Chemical	Ethylcellulose	9004-57-3		0.0026 mg	4.303 %
		Protective Coat_Coating	0.0652 mg	Chemical	Frits, chemicals (Pb-free)	65997-18-4		0.0572 mg	94.9992 %
				Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.0137 mg	20.9969 %
				Chemical	C.I. Pigment Black 28	68186-91-4		0.0091 mg	14.0031 %
				Chemical	Formaldehyde, polymer with 1,3-dimethylbenzene and phenol	29661-89-0		0.0163 mg	25 %
		Marking_Marking	0.0017 mg	Chemical	Silica Fused	60676-86-0		0.0222 mg	34.0031 %
				Chemical	Talc	14807-96-6		0.0039 mg	5.9969 %
				Oxide	Amorphous silicon dioxide	112945-52-5		0.0001 mg	3.5714 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		0.0006 mg	35.119 %
		Side Termination_Epoxy, Silver Filled	0.0961 mg	Chemical	Talc	14807-96-6		0.0001 mg	3.5714 %
				Oxide	Titanium dioxide	13463-67-7		0.001 mg	57.7381 %
				Chemical	Alkyl Phenol Resin	26834-02-6		0.0163 mg	16.996 %
				Metal	Silver	7440-22-4		0.0798 mg	83.004 %
		Under Plating_Nickel	0.0109 mg	Nickel/Nickel Compounds	Nickel	7440-02-0		0.0109 mg	100 %
		Plating_Matte Tin	0.0075 mg	Metal	Tin	7440-31-5		0.0075 mg	100 %
		Element_Ceramic	0.989 mg	Oxide	Iron (III) oxide	1309-37-1		0.1978 mg	20 %
206415	8.5057 mg	Substrate_Ceramic	7.6146 mg	Oxide	Manganese Oxide (Mn3O4)	1317-35-7		0.4945 mg	50 %
				Nickel/Nickel Compounds	Nickel (II) oxide	1313-99-1		0.2967 mg	30 %
				Under Plating_Nickel	Nickel/Nickel Compounds	Nickel	7440-02-0	0.0133 mg	100 %
				Plating_Matte Tin	Metal	Tin	7440-31-5	0.03 mg	100 %
		Inner Electrode_Metal Alloy	0.022 mg	Metal	Palladium	7440-05-3		0.0154 mg	70 %
				Metal	Silver	7440-22-4		0.0066 mg	30 %
		Outer Electrode_Silver Alloy	0.0893 mg	Metal	Palladium	7440-05-3		0.0045 mg	5 %
				Metal	Silver	7440-22-4		0.0848 mg	95 %
		Outer Electrode_Glass	0.0057 mg	Chemical	Boron Trioxide	1303-86-2		0.0015 mg	26 %
				Chemical	Silica	7631-86-9		0.0042 mg	74 %
		Inner Electrode_Glass and Metal	0.038 mg	Ceramics / Glass	Alumina	1344-28-1		7.31 mg	96.0001 %
				Oxide	Magnesium Oxide	1309-48-4		0.1523 mg	2 %
				Chemical	Silica	7631-86-9		0.1523 mg	2 %
				Metal	Palladium	7440-05-3		0.0005 mg	1.4196 %
		Inner Electrode_Silver	0.0194 mg	Metal	Silver	7440-22-4		0.0375 mg	98.5804 %
				Metal	Silver	7440-22-4		0.0194 mg	100 %
		Resistive Layer_Glass and Metal	0.0436 mg	Lead/Lead Compounds	Frits, Chemicals (Leaded)	65997-18-4	7(c)-I	0.0018 mg	4.0092 %
				Oxide	Ruthenium dioxide	12036-10-1		0.0332 mg	75.9908 %
				Metal	Silver	7440-22-4		0.0087 mg	20 %
				Plating_Nickel Barrier	Nickel/Nickel Compounds	Nickel	7440-02-0	0.2444 mg	100 %
		Plating_Matte Tin	0.2108 mg	Metal	Tin	7440-31-5		0.2108 mg	100 %
		Primary glass_Glass	0.0635 mg	Bismuth/Bismuth Compounds	Bismuth trioxide	1304-76-3		0.0489 mg	77.0043 %
				Metalloid	Boron	7440-42-8		0.0051 mg	8.0013 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
206415	8.484 mg	Overcoat_Epoxy Resin	0.2698 mg	Chemical	Silica Fused	60676-86-0		0.0095 mg	14.9945 %
				Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.054 mg	20.0007 %
		Marking_Epoxy Resin	0.0014 mg	Chemical	C.I. Pigment Black 28	68186-91-4		0.2159 mg	79.9993 %
				Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.0014 mg	100 %
		Substrate_Ceramic	8.0655 mg	Ceramics / Glass	Alumina	1344-28-1		7.7211 mg	95.7301 %
				Oxide	Calcium oxide	1305-78-8		0.1484 mg	1.8398 %
				Oxide	Magnesium Oxide	1309-48-4		0.0476 mg	0.5903 %
		Backside Layer_Paste	0.0176 mg	Oxide	Silicon dioxide	14808-60-7		0.1484 mg	1.8398 %
				Chemical	Ethylcellulose	9004-57-3		0.0018 mg	10.0228 %
				Chemical	Frits, chemicals (Pb-free)	65997-18-4		0.0019 mg	10.9909 %
		Topside Layer_Paste	0.1142 mg	Nickel/Nickel Compounds	Nickel	7440-02-0		0.001 mg	5.9795 %
				Metal	Silver	7440-22-4		0.0128 mg	73.0068 %
				Chemical	Ethylcellulose	9004-57-3			
		Resistive Layer_Glass and Metal	0.0452 mg	Chemical	Frits, chemicals (Pb-free)	65997-18-4		0.0138 mg	12.1148 %
				Metal	Palladium	7440-05-3		0.0007 mg	0.6303 %
				Metal	Silver	7440-22-4		0.0997 mg	87.2549 %
		Primary Coating_Coating	0.0602 mg	Chemical	Frits, chemicals (Pb-free)	65997-18-4		0.003 mg	6.6667 %
				Lead/Lead Compounds	Lead (II) Oxide	1317-36-8	7(c)-I	0.0075 mg	16.6556 %
				Metal	Palladium	7440-05-3		0.006 mg	13.3333 %
				Oxide	Ruthenium dioxide	12036-10-1		0.0023 mg	5.0055 %
				Chemical	Silica	7631-86-9		0.0113 mg	25.0055 %
206418	3.783 mg	Protective Coat_Coating	0.0652 mg	Metal	Silver	7440-22-4		0.015 mg	33.3333 %
				Oxide	Chromium Oxide	1308-38-9		0.0004 mg	0.6978 %
				Chemical	Ethylcellulose	9004-57-3		0.0026 mg	4.303 %
				Chemical	Frits, chemicals (Pb-free)	65997-18-4		0.0572 mg	94.9992 %
				Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.0137 mg	20.9969 %
		Marking_Marking	0.0017 mg	Chemical	C.I. Pigment Black 28	68186-91-4		0.0091 mg	14.0031 %
				Chemical	Formaldehyde, polymer with 1,3-dimethylbenzene and phenol	29661-89-0		0.0163 mg	25 %
				Chemical	Silica Fused	60676-86-0		0.0222 mg	34.0031 %
				Chemical	Talc	14807-96-6		0.0039 mg	5.9969 %
				Oxide	Amorphous silicon dioxide	112945-52-5		0.0001 mg	3.5714 %
		Side Termination_Epoxy, Silver Filled	0.0961 mg	Chemical	Epoxy Cresol Novolac	29690-82-2		0.0006 mg	35.119 %
				Chemical	Talc	14807-96-6		0.0001 mg	3.5714 %
				Oxide	Titanium dioxide	13463-67-7		0.001 mg	57.7381 %
				Chemical	Alkyl Phenol Resin	26834-02-6		0.0163 mg	16.996 %
				Metal	Silver	7440-22-4		0.0798 mg	83.004 %
		Under Plating_Nickel	0.0109 mg	Nickel/Nickel Compounds	Nickel	7440-02-0		0.0109 mg	100 %
		Plating_Matte Tin	0.0075 mg	Metal	Tin	7440-31-5		0.0075 mg	100 %
		Die_Doped Silicon	0.05 mg	Metalloid	Silicon	7440-21-3		0.05 mg	100 %
				Copper and its alloys	Copper	7440-50-8		1.4745 mg	97.7286 %
				Metal	Iron	7439-89-6		0.0319 mg	2.1116 %
		Lead Frame_Copper Alloy	1.5088 mg	Chemical	Phosphorus	7723-14-0		0.0004 mg	0.0298 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
				Zinc and its alloys	Zinc	7440-66-6		0.002 mg	0.1299 %
				Metal	Silver	7440-22-4		0.0012 mg	100 %
				Chemical	Carbon Black	1333-86-4		0.0064 mg	0.3 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		0.3745 mg	17.5 %
				Chemical	Phenolic Novolac	9003-35-4		0.1519 mg	7.1 %
				Chemical	Silica Fused	60676-86-0		1.6071 mg	75.1 %
		Wire_Copper	0.003 mg	Copper and its alloys	Copper	7440-50-8		0.003 mg	100 %
		Post-Plating_Matte Tin	0.08 mg	Antimony/Antimony Compounds	Antimony	7440-36-0		0 mg	0.0125 %
				Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0 mg	0.025 %
				Metal	Iron	7439-89-6		0 mg	0.0125 %
				Lead/Lead Compounds	Lead	7439-92-1		0 mg	0.0125 %
				Metal	Tin	7440-31-5		0.08 mg	99.9375 %
206418	3.783 mg	Die_Doped Silicon	0.05 mg	Metalloid	Silicon	7440-21-3		0.05 mg	100 %
		Lead Frame_Copper Alloy	1.5088 mg	Copper and its alloys	Copper	7440-50-8		1.4745 mg	97.7286 %
				Metal	Iron	7439-89-6		0.0319 mg	2.1116 %
				Chemical	Phosphorus	7723-14-0		0.0004 mg	0.0298 %
				Zinc and its alloys	Zinc	7440-66-6		0.002 mg	0.1299 %
		Lead Frame_Silver	0.0012 mg	Metal	Silver	7440-22-4		0.0012 mg	100 %
		Mold Compound_Epoxy with Silica Filler	2.14 mg	Chemical	Carbon Black	1333-86-4		0.0064 mg	0.3 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		0.3745 mg	17.5 %
				Chemical	Phenolic Novolac	9003-35-4		0.1519 mg	7.1 %
				Chemical	Silica Fused	60676-86-0		1.6071 mg	75.1 %
		Wire_Copper	0.003 mg	Copper and its alloys	Copper	7440-50-8		0.003 mg	100 %
		Post-Plating_Matte Tin	0.08 mg	Antimony/Antimony Compounds	Antimony	7440-36-0		0 mg	0.0125 %
				Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0 mg	0.025 %
				Metal	Iron	7439-89-6		0 mg	0.0125 %
				Lead/Lead Compounds	Lead	7439-92-1		0 mg	0.0125 %
				Metal	Tin	7440-31-5		0.08 mg	99.9375 %
206418	3.783 mg	Die_Doped Silicon	0.05 mg	Metalloid	Silicon	7440-21-3		0.05 mg	100 %
		Lead Frame_Copper Alloy	1.5088 mg	Copper and its alloys	Copper	7440-50-8		1.4745 mg	97.7286 %
				Metal	Iron	7439-89-6		0.0319 mg	2.1116 %
				Chemical	Phosphorus	7723-14-0		0.0004 mg	0.0298 %
				Zinc and its alloys	Zinc	7440-66-6		0.002 mg	0.1299 %
		Lead Frame_Silver	0.0012 mg	Metal	Silver	7440-22-4		0.0012 mg	100 %
		Mold Compound_Epoxy with Silica Filler	2.14 mg	Chemical	Carbon Black	1333-86-4		0.0064 mg	0.3 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		0.3745 mg	17.5 %
				Chemical	Phenolic Novolac	9003-35-4		0.1519 mg	7.1 %
				Chemical	Silica Fused	60676-86-0		1.6071 mg	75.1 %
		Wire_Copper	0.003 mg	Copper and its alloys	Copper	7440-50-8		0.003 mg	100 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
		Post-Plating_Matte Tin	0.08 mg	Antimony/Antimony Compounds	Antimony	7440-36-0		0 mg	0.0125 %
				Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0 mg	0.025 %
				Metal	Iron	7439-89-6		0 mg	0.0125 %
				Lead/Lead Compounds	Lead	7439-92-1		0 mg	0.0125 %
				Metal	Tin	7440-31-5		0.08 mg	99.9375 %
210147	53.4241 mg	Bond Wire_Copper Alloy	0.1062 mg	Copper and its alloys	Copper	7440-50-8		0.1035 mg	97.5339 %
				Precious metals	Gold	7440-57-5		0.0001 mg	0.0518 %
				Chemical	Miscellaneous and Proprietary			0 mg	0.0113 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0 mg	0.0009 %
				Metal	Palladium	7440-05-3		0.0025 mg	2.3993 %
				Metal	Silver	7440-22-4		0 mg	0.0028 %
		Die Attach_Epoxy with Silica Filler	0.2933 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.1584 mg	53.9999 %
				Chemical	Imidazole	288-32-4		0.0029 mg	1.0001 %
				Chemical	Silica	7631-86-9		0.132 mg	45 %
		Die Attach 2_Epoxy with Silica Filler	0.3143 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.1697 mg	54.0002 %
				Chemical	Imidazole	288-32-4		0.0031 mg	0.9998 %
				Chemical	Silica	7631-86-9		0.1415 mg	45 %
		Lead Frame_Copper Alloy	29.84 mg	Copper and its alloys	Copper	7440-50-8		29.1 mg	97.52 %
				Metal	Iron	7439-89-6		0.6863 mg	2.3 %
				Chemical	Phosphorus	7723-14-0		0.009 mg	0.03 %
				Zinc and its alloys	Zinc	7440-66-6		0.0448 mg	0.15 %
		Lead Frame Plating_Metal	0.87 mg	Precious metals	Gold	7440-57-5		0.0068 mg	0.78 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.8275 mg	95.12 %
				Metal	Palladium	7440-05-3		0.0357 mg	4.1 %
		Mold Compound_Epoxy with Silica Filler	18.4152 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		2.1544 mg	11.699 %
				Chemical	Carbon Black	1333-86-4		0.0552 mg	0.3 %
				Chemical	Chlorine	7782-50-5		0.0002 mg	0.001 %
				Chemical	Silica Fused	60676-86-0		16.2053 mg	88 %
		Semiconductor Device_Doped Silicon	1.7304 mg	Metalloid	Silicon	7440-21-3		1.7304 mg	100 %
		Semiconductor Device 2_Doped Silicon	1.8547 mg	Metalloid	Silicon	7440-21-3		1.8547 mg	100 %
210147	53.4241 mg	Bond Wire_Copper Alloy	0.1062 mg	Copper and its alloys	Copper	7440-50-8		0.1035 mg	97.5339 %
				Precious metals	Gold	7440-57-5		0.0001 mg	0.0518 %
				Chemical	Miscellaneous and Proprietary			0 mg	0.0113 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0 mg	0.0009 %
				Metal	Palladium	7440-05-3		0.0025 mg	2.3993 %
				Metal	Silver	7440-22-4		0 mg	0.0028 %
		Die Attach_Epoxy with Silica Filler	0.2933 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.1584 mg	53.9999 %
				Chemical	Imidazole	288-32-4		0.0029 mg	1.0001 %
				Chemical	Silica	7631-86-9		0.132 mg	45 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
		Die Attach 2_Epoxy with Silica Filler	0.3143 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.1697 mg	54.0002 %
				Chemical	Imidazole	288-32-4		0.0031 mg	0.9998 %
				Chemical	Silica	7631-86-9		0.1415 mg	45 %
		Lead Frame_Copper Alloy	29.84 mg	Copper and its alloys	Copper	7440-50-8		29.1 mg	97.52 %
				Metal	Iron	7439-89-6		0.6863 mg	2.3 %
				Chemical	Phosphorus	7723-14-0		0.009 mg	0.03 %
				Zinc and its alloys	Zinc	7440-66-6		0.0448 mg	0.15 %
		Lead Frame Plating_Metal	0.87 mg	Precious metals	Gold	7440-57-5		0.0068 mg	0.78 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.8275 mg	95.12 %
				Metal	Palladium	7440-05-3		0.0357 mg	4.1 %
		Mold Compound_Epoxy with Silica Filler	18.4152 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		2.1544 mg	11.699 %
				Chemical	Carbon Black	1333-86-4		0.0552 mg	0.3 %
				Chemical	Chlorine	7782-50-5		0.0002 mg	0.001 %
				Chemical	Silica Fused	60676-86-0		16.2053 mg	88 %
		Semiconductor Device_Doped Silicon	1.7304 mg	Metalloid	Silicon	7440-21-3		1.7304 mg	100 %
		Semiconductor Device 2_Doped Silicon	1.8547 mg	Metalloid	Silicon	7440-21-3		1.8547 mg	100 %
210147	53.4241 mg	Bond Wire_Copper Alloy	0.1062 mg	Copper and its alloys	Copper	7440-50-8		0.1035 mg	97.5339 %
				Precious metals	Gold	7440-57-5		0.0001 mg	0.0518 %
				Chemical	Miscellaneous and Proprietary			0 mg	0.0113 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0 mg	0.0009 %
				Metal	Palladium	7440-05-3		0.0025 mg	2.3993 %
				Metal	Silver	7440-22-4		0 mg	0.0028 %
		Die Attach_Epoxy with Silica Filler	0.2933 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.1584 mg	53.9999 %
				Chemical	Imidazole	288-32-4		0.0029 mg	1.0001 %
				Chemical	Silica	7631-86-9		0.132 mg	45 %
		Die Attach 2_Epoxy with Silica Filler	0.3143 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.1697 mg	54.0002 %
				Chemical	Imidazole	288-32-4		0.0031 mg	0.9998 %
				Chemical	Silica	7631-86-9		0.1415 mg	45 %
		Lead Frame_Copper Alloy	29.84 mg	Copper and its alloys	Copper	7440-50-8		29.1 mg	97.52 %
				Metal	Iron	7439-89-6		0.6863 mg	2.3 %
				Chemical	Phosphorus	7723-14-0		0.009 mg	0.03 %
				Zinc and its alloys	Zinc	7440-66-6		0.0448 mg	0.15 %
		Lead Frame Plating_Metal	0.87 mg	Precious metals	Gold	7440-57-5		0.0068 mg	0.78 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.8275 mg	95.12 %
				Metal	Palladium	7440-05-3		0.0357 mg	4.1 %
		Mold Compound_Epoxy with Silica Filler	18.4152 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		2.1544 mg	11.699 %
				Chemical	Carbon Black	1333-86-4		0.0552 mg	0.3 %
				Chemical	Chlorine	7782-50-5		0.0002 mg	0.001 %
				Chemical	Silica Fused	60676-86-0		16.2053 mg	88 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
		Semiconductor Device_Doped Silicon	1.7304 mg	Metalloid	Silicon	7440-21-3		1.7304 mg	100 %
		Semiconductor Device 2_Doped Silicon	1.8547 mg	Metalloid	Silicon	7440-21-3		1.8547 mg	100 %
210723	8.99 mg	Chip_Silicon	0.5 mg	Metalloid	Silicon	7440-21-3		0.5 mg	100 %
		Lead Frame_Copper Alloy	2.41 mg	Copper and its alloys	Copper	7440-50-8		2.29 mg	95.0207 %
				Metal	Iron	7439-89-6		0.12 mg	4.9793 %
		Bond Wire_Metal	0.1 mg	Precious metals	Copper or Gold	7440-50-8 or 7440-57-5		0.1 mg	100 %
		Encapsulation_Epoxy with Silica Filler	5.48 mg	Chemical	Epoxy			1.37 mg	25 %
				Chemical	Others			0.25 mg	4.562 %
				Chemical	Silica	7631-86-9		3.86 mg	70.438 %
		Lead Finish_Matte Tin	0.43 mg	Metal	Tin	7440-31-5		0.43 mg	100 %
		Die Attach_Epoxy, Silver Filled	0.07 mg	Chemical	Phenol, 4,4'-(1-methylethylidene)bis-, polymer with (chloromethyl)oxirane, 2-propenoate	90598-46-2		0.02 mg	28.5714 %
				Metal	Silver	7440-22-4		0.05 mg	71.4286 %
210728									
210728									
210729									
210742	17 mg	Plating_Matte Tin	1.6681 mg	Metal	Tin	7440-31-5		1.6681 mg	100 %
		Element_Ceramic	15.2575 mg	Ceramics / Glass	Barium titanate	12047-27-7		13.5792 mg	89 %
				Lead/Lead Compounds	Lead (II) Oxide	1317-36-8	7(c)-I	1.5257 mg	10 %
				Oxide	Samarium oxide	12060-58-1		0.1526 mg	1 %
		Electrode_Silver	0.0267 mg	Metal	Silver	7440-22-4		0.0267 mg	100 %
		Electrode_Chromium	0.0078 mg	Metal	Chromium	7440-47-3		0.0078 mg	100 %
		Electrode_Metal Alloy	0.0399 mg	Copper and its alloys	Copper	7440-50-8		0.012 mg	30 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.0279 mg	70 %
210788-02									
210789-01									
210790-01									
210791-03									
210792-02									
210793-01									
210794-03									
210795-03									
210796-03									
210801-01									
210823-01									
210823-01									
210838									
210838									
210855									
210855									
210928									

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
210928									
211347	33.92 mg	Die_Doped Silicon	1.08 mg	Metalloid	Silicon	7440-21-3		1.08 mg	100 %
		Clip_Copper Alloy	6.85 mg	Copper and its alloys	Copper	7440-50-8		6.8411 mg	99.8699 %
				Metal	Iron	7439-89-6		0.0068 mg	0.1 %
				Chemical	Phosphorus compounds			0.0021 mg	0.0301 %
		Mold Compound_Epoxy with Silica Filler	11.32 mg	Chemical	Carbon Black	1333-86-4		0.034 mg	0.3 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		2.23 mg	19.7 %
				Chemical	Phenolic Resin			1.0188 mg	9 %
				Chemical	Silica Fused	60676-86-0		8.0372 mg	71 %
		Post-Plating_Tin Plating	0.35 mg	Antimony/Antimony Compounds	Antimony	7440-36-0		0 mg	0.0029 %
				Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0 mg	0.001 %
				Copper and its alloys	Copper	7440-50-8		0 mg	0.001 %
				Lead/Lead Compounds	Lead	7439-92-1		0 mg	0.0057 %
				Metal	Tin	7440-31-5		0.35 mg	99.9895 %
		Solder Paste_Solder	2.5 mg	Lead/Lead Compounds	Lead	7439-92-1	7(a)	2.3125 mg	92.5 %
				Metal	Silver	7440-22-4		0.0625 mg	2.5 %
				Metal	Tin	7440-31-5		0.125 mg	5 %
		Lead Frame_Copper Alloy	11.6486 mg	Copper and its alloys	Copper	7440-50-8		11.6332 mg	99.8681 %
				Metal	Iron	7439-89-6		0.0118 mg	0.1015 %
				Chemical	Phosphorus compounds			0.0035 mg	0.0305 %
		Lead Frame_Silver Plating	0.1714 mg	Metal	Silver	7440-22-4		0.1714 mg	100 %
211347									
211347	33.92 mg	Die_Doped Silicon	1.08 mg	Metalloid	Silicon	7440-21-3		1.08 mg	100 %
		Lead Frame_Copper Alloy	11.6486 mg	Copper and its alloys	Copper	7440-50-8		11.6332 mg	99.8681 %
				Metal	Iron	7439-89-6		0.0118 mg	0.1015 %
				Chemical	Phosphorus	7723-14-0		0.0035 mg	0.0305 %
		Mold Compound_Epoxy with Silica Filler	11.32 mg	Chemical	Carbon Black	1333-86-4		0.034 mg	0.3 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		2.23 mg	19.7 %
				Chemical	Phenolic Resin			1.0188 mg	9 %
				Chemical	Silica Fused	60676-86-0		8.0372 mg	71 %
		Post-Plating_Matte Tin	0.35 mg	Antimony/Antimony Compounds	Antimony	7440-36-0		0 mg	0.0029 %
				Bismuth/Bismuth Compounds	Bismuth	7440-69-9			
				Copper and its alloys	Copper	7440-50-8			
				Lead/Lead Compounds	Lead	7439-92-1		0 mg	0.0057 %
				Metal	Tin	7440-31-5		0.35 mg	99.9914 %
		Solder Paste_High Temperature Solder	2.5 mg	Lead/Lead Compounds	Lead	7439-92-1	7(a)	2.3125 mg	92.5 %
				Metal	Silver	7440-22-4		0.0625 mg	2.5 %
				Metal	Tin	7440-31-5		0.125 mg	5 %
		Clip_Copper Alloy	6.85 mg	Copper and its alloys	Copper	7440-50-8		6.8411 mg	99.8699 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration	
211347	45.9731 mg			Metal	Iron	7439-89-6		0.0068 mg	0.1 %	
				Chemical	Phosphorus	7723-14-0		0.0021 mg	0.0301 %	
		Lead Frame_Silver	0.1714 mg	Metal	Silver	7440-22-4		0.1714 mg	100 %	
		Mold Compound_Epoxy with Silica Filler	18.88 mg	Ceramics / Glass	Aluminum hydroxide	21645-51-2		2.4725 mg	13.0959 %	
			Chemical	Carbon Black	1333-86-4		0.057 mg	0.3019 %		
			Chemical	Epoxy Resin 1			1.7756 mg	9.4047 %		
			Chemical	Epoxy Resin 2			0.5572 mg	2.9513 %		
			Chemical	Silica Fused	60676-86-0		14.0177 mg	74.2463 %		
		Lead Frame_Copper Alloy	24.998 mg	Copper and its alloys	Copper	7440-50-8		24.403 mg	97.6198 %	
			Metal	Iron	7439-89-6		0.55 mg	2.2002 %		
			Chemical	Phosphorus	7723-14-0		0.0075 mg	0.03 %		
			Zinc and its alloys	Zinc	7440-66-6		0.0375 mg	0.15 %		
		External Plating_Tin Plating	0.61 mg	Metal	Tin	7440-31-5		0.61 mg	100 %	
		Die_Doped Silicon	0.872 mg	Metalloid	Silicon	7440-21-3		0.623 mg	71.445 %	
			Metal	Silver	7440-22-4		0.249 mg	28.555 %		
Die Attach_High Temperature Solder	0.6131 mg		Lead/Lead Compounds	Lead	7439-92-1	7(a)	0.5732 mg	93.4921 %		
	Metal		Silver	7440-22-4		0.0092 mg	1.5006 %			
	Metal	Tin	7440-31-5		0.0307 mg	5.0073 %				
211347										
211347										
211373	45.9731 mg	Mold Compound_Epoxy with Silica Filler	18.88 mg	Ceramics / Glass	Aluminum hydroxide	21645-51-2		2.4725 mg	13.0959 %	
				Chemical	Carbon Black	1333-86-4		0.057 mg	0.3019 %	
				Chemical	Epoxy Resin 1			1.7756 mg	9.4047 %	
				Chemical	Epoxy Resin 2			0.5572 mg	2.9513 %	
				Chemical	Silica Fused	60676-86-0		14.0177 mg	74.2463 %	
		Lead Frame_Copper Alloy	24.998 mg	Copper and its alloys	Copper	7440-50-8		24.403 mg	97.6198 %	
			Metal	Iron	7439-89-6		0.55 mg	2.2002 %		
			Chemical	Phosphorus	7723-14-0		0.0075 mg	0.03 %		
			Zinc and its alloys	Zinc	7440-66-6		0.0375 mg	0.15 %		
		External Plating_Tin Plating	0.61 mg	Metal	Tin	7440-31-5		0.61 mg	100 %	
		Die_Doped Silicon	0.872 mg	Metalloid	Silicon	7440-21-3		0.623 mg	71.445 %	
			Metal	Silver	7440-22-4		0.249 mg	28.555 %		
			Die Attach_High Temperature Solder	0.6131 mg	Lead/Lead Compounds	Lead	7439-92-1	7(a)	0.5732 mg	93.4921 %
				Metal	Silver	7440-22-4		0.0092 mg	1.5006 %	
		Metal		Tin	7440-31-5		0.0307 mg	5.0073 %		
		211373	45.9731 mg	Mold Compound_Epoxy with Silica Filler	18.88 mg	Ceramics / Glass	Aluminum hydroxide	21645-51-2		2.4725 mg
				Chemical	Carbon Black	1333-86-4		0.057 mg	0.3019 %	
				Chemical	Epoxy Resin 1			1.7756 mg	9.4047 %	
				Chemical	Epoxy Resin 2			0.5572 mg	2.9513 %	
				Chemical	Silica Fused	60676-86-0		14.0177 mg	74.2463 %	

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration		
		Lead Frame_Copper Alloy	24.998 mg	Copper and its alloys	Copper	7440-50-8		24.403 mg	97.6198 %		
				Metal	Iron	7439-89-6		0.55 mg	2.2002 %		
				Chemical	Phosphorus	7723-14-0		0.0075 mg	0.03 %		
				Zinc and its alloys	Zinc	7440-66-6		0.0375 mg	0.15 %		
		External Plating_Tin Plating	0.61 mg	Metal	Tin	7440-31-5		0.61 mg	100 %		
		Die_Doped Silicon	0.872 mg	Metalloid	Silicon	7440-21-3		0.623 mg	71.445 %		
				Metal	Silver	7440-22-4		0.249 mg	28.555 %		
				Die Attach_High Temperature Solder	0.6131 mg	Lead/Lead Compounds	Lead	7439-92-1	7(a)	0.5732 mg	93.4921 %
						Metal	Silver	7440-22-4		0.0092 mg	1.5006 %
		Metal	Tin			7440-31-5		0.0307 mg	5.0073 %		
211395	9.1749 mg	Bond Wire_Copper Alloy	0.0805 mg	Copper and its alloys	Copper	7440-50-8		0.079 mg	98.1974 %		
				Metal	Palladium	7440-05-3		0.0015 mg	1.8026 %		
				Die Attach_Epoxy, Silver Filled	0.1575 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.0394 mg	25 %
				Metal	Silver	7440-22-4		0.1181 mg	75 %		
				Lead Frame_Copper Alloy	4.6 mg	Copper and its alloys	Copper	7440-50-8		4.4836 mg	97.47 %
						Metal	Iron	7439-89-6		0.1049 mg	2.28 %
		Chemical	Phosphorus			7723-14-0		0.0046 mg	0.1 %		
		Zinc and its alloys	Zinc			7440-66-6		0.0069 mg	0.15 %		
		Lead Frame Plating_Metal	0.01 mg	Precious metals	Gold	7440-57-5		0.0001 mg	0.78 %		
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.0095 mg	95.12 %		
				Metal	Palladium	7440-05-3		0.0004 mg	4.1 %		
				Mold Compound_Epoxy with Silica Filler	3.7679 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.4145 mg	11 %
				Chemical	Carbon Black	1333-86-4		0.0188 mg	0.5 %		
				Chemical	Silica Fused	60676-86-0		3.3157 mg	88 %		
				Chemical	Siloxanes and Silicones, di-Me, hydrogen-terminated, reaction products with epichlorohydrin, formaldehyde-phenol polymer and [(2-propenyloxy)methyl]oxirane	218163-11-2		0.0075 mg	0.2 %		
				Chemical	Tricresyl phosphate	1330-78-5		0.0113 mg	0.3 %		
		Semiconductor Device_Doped Silicon	0.559 mg	Metalloid	Silicon	7440-21-3		0.559 mg	100 %		
		211395	9.1749 mg	Bond Wire_Copper Alloy	0.0805 mg	Copper and its alloys	Copper	7440-50-8		0.079 mg	98.1974 %
				Metal	Palladium	7440-05-3		0.0015 mg	1.8026 %		
				Die Attach_Epoxy, Silver Filled	0.1575 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.0394 mg	25 %
				Metal	Silver	7440-22-4		0.1181 mg	75 %		
				Lead Frame_Copper Alloy	4.6 mg	Copper and its alloys	Copper	7440-50-8		4.4836 mg	97.47 %
						Metal	Iron	7439-89-6		0.1049 mg	2.28 %
		Chemical	Phosphorus			7723-14-0		0.0046 mg	0.1 %		
		Zinc and its alloys	Zinc			7440-66-6		0.0069 mg	0.15 %		
		Lead Frame Plating_Metal	0.01 mg	Precious metals	Gold	7440-57-5		0.0001 mg	0.78 %		
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.0095 mg	95.12 %		
				Metal	Palladium	7440-05-3		0.0004 mg	4.1 %		

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
211419	0.9102 mg	Mold Compound_Epoxy with Silica Filler	3.7679 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.4145 mg	11 %
				Chemical	Carbon Black	1333-86-4		0.0188 mg	0.5 %
				Chemical	Silica Fused	60676-86-0		3.3157 mg	88 %
				Chemical	Siloxanes and Silicones, di-Me, hydrogen-terminated, reaction products with epichlorohydrin, formaldehyde-phenol polymer and [(2-propenyloxy)methyl]oxirane	218163-11-2		0.0075 mg	0.2 %
				Chemical	Tricresyl phosphate	1330-78-5		0.0113 mg	0.3 %
		Semiconductor Device_Doped Silicon	0.559 mg	Metalloid	Silicon	7440-21-3		0.559 mg	100 %
		Bond Wire_Gold	0.0034 mg	Precious metals	Gold	7440-57-5		0.0034 mg	100 %
		Die Attach_Epoxy, Silver Filled	0.0116 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.0013 mg	11.0003 %
				Chemical	Alkanes, C10-13-iso-	68551-17-7		0.0001 mg	0.9969 %
				Chemical	Filler			0.0008 mg	7.0041 %
				Chemical	Hydroxypropyl methacrylate	27813-02-1		0.0001 mg	0.9969 %
				Metal	Silver	7440-22-4		0.0093 mg	80.0017 %
		Lead Frame_Copper Alloy	0.6 mg	Copper and its alloys	Copper	7440-50-8		0.5847 mg	97.45 %
				Metal	Iron	7439-89-6		0.0138 mg	2.3 %
				Chemical	Phosphorus	7723-14-0		0.0006 mg	0.1 %
				Zinc and its alloys	Zinc	7440-66-6		0.0009 mg	0.15 %
		Lead Frame Plating_Metal	0.03 mg	Precious metals	Gold	7440-57-5		0.0002 mg	0.78 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.0285 mg	95.12 %
				Metal	Palladium	7440-05-3		0.0012 mg	4.1 %
		Mold Compound_Epoxy with Silica Filler	0.2226 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.0174 mg	7.8002 %
				Chemical	Carbon Black	1333-86-4		0.0011 mg	0.5 %
				Chemical	Proprietary Non Halide			0.0027 mg	1.1999 %
				Chemical	Silica Fused	60676-86-0		0.2003 mg	90 %
				Chemical	Tricresyl phosphate	1330-78-5		0.0011 mg	0.5 %
		Semiconductor Device_Doped Silicon	0.0425 mg	Metalloid	Silicon	7440-21-3		0.0425 mg	100 %
211419	0.9476 mg	Die_Doped Silicon	0.0186 mg	Metalloid	Silicon	7440-21-3		0.0186 mg	100 %
		Lead Frame_Copper Alloy	0.4275 mg	Copper and its alloys	Copper	7440-50-8		0.4242 mg	99.2281 %
				Magnesium and its alloys	Magnesium	7439-95-4		0.0004 mg	0.1029 %
				Metalloid	Silicon	7440-21-3		0.0029 mg	0.669 %
		Wire_Doped Gold	0.004 mg	Precious metals	Gold	7440-57-5		0.004 mg	100 %
		Molding Compound_Epoxy with Silica Filler	0.48 mg	Chemical	Carbon Black	1333-86-4		0.0012 mg	0.25 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		0.0648 mg	13.5 %
				Chemical	Epoxy Resin			0.0144 mg	3 %
				Chemical	Phenolic Resin			0.0144 mg	3 %
				Chemical	Silica Fused	60676-86-0		0.3852 mg	80.25 %
		Lead Frame_Plating	0.0125 mg	Precious metals	Gold	7440-57-5		0 mg	0.3521 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.012 mg	96.1268 %
				Metal	Palladium	7440-05-3		0.0004 mg	3.5211 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
		Adhesive_Other	0.005 mg	Chemical	2-Propenenitrile, polymer with 1,3-butadiene, carboxy-terminated, polymers with bisphenol A and epichlorohydrin	68610-41-3		0.0004 mg	8 %
				Chemical	Bisphenol A diglycidyl ether polymer	25036-25-3		0.0002 mg	4 %
				Chemical	Diethylene glycol monoethyl ether acetate	112-15-2		0.0003 mg	7 %
				Chemical	Formaldehyde, polymer with benzenamine, maleated, cyclized	67784-74-1		0.0002 mg	4 %
				Chemical	Miscellaneous and Proprietary			0.0001 mg	2 %
211419	0.9102 mg			Metal	Silver	7440-22-4		0.0038 mg	75 %
		Bond Wire_Gold	0.0034 mg	Precious metals	Gold	7440-57-5		0.0034 mg	100 %
		Die Attach_Epoxy, Silver Filled	0.0116 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.0013 mg	11.0003 %
				Chemical	Alkanes, C10-13-iso-	68551-17-7		0.0001 mg	0.9969 %
				Chemical	Filler			0.0008 mg	7.0041 %
				Chemical	Hydroxypropyl methacrylate	27813-02-1		0.0001 mg	0.9969 %
				Metal	Silver	7440-22-4		0.0093 mg	80.0017 %
		Lead Frame_Copper Alloy	0.6 mg	Copper and its alloys	Copper	7440-50-8		0.5847 mg	97.45 %
				Metal	Iron	7439-89-6		0.0138 mg	2.3 %
				Chemical	Phosphorus	7723-14-0		0.0006 mg	0.1 %
				Zinc and its alloys	Zinc	7440-66-6		0.0009 mg	0.15 %
		Lead Frame Plating_Metal	0.03 mg	Precious metals	Gold	7440-57-5		0.0002 mg	0.78 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.0285 mg	95.12 %
				Metal	Palladium	7440-05-3		0.0012 mg	4.1 %
		Mold Compound_Epoxy with Silica Filler	0.2226 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.0174 mg	7.8002 %
				Chemical	Carbon Black	1333-86-4		0.0011 mg	0.5 %
				Chemical	Proprietary Non Halide			0.0027 mg	1.1999 %
				Chemical	Silica Fused	60676-86-0		0.2003 mg	90 %
				Chemical	Tricresyl phosphate	1330-78-5		0.0011 mg	0.5 %
211419	0.9102 mg	Semiconductor Device_Doped Silicon	0.0425 mg	Metalloid	Silicon	7440-21-3		0.0425 mg	100 %
		Bond Wire_Gold	0.0034 mg	Precious metals	Gold	7440-57-5		0.0034 mg	100 %
		Die Attach_Epoxy, Silver Filled	0.0116 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.0013 mg	11.0003 %
				Chemical	Alkanes, C10-13-iso-	68551-17-7		0.0001 mg	0.9969 %
				Chemical	Filler			0.0008 mg	7.0041 %
				Chemical	Hydroxypropyl methacrylate	27813-02-1		0.0001 mg	0.9969 %
				Metal	Silver	7440-22-4		0.0093 mg	80.0017 %
		Lead Frame_Copper Alloy	0.6 mg	Copper and its alloys	Copper	7440-50-8		0.5847 mg	97.45 %
				Metal	Iron	7439-89-6		0.0138 mg	2.3 %
				Chemical	Phosphorus	7723-14-0		0.0006 mg	0.1 %
				Zinc and its alloys	Zinc	7440-66-6		0.0009 mg	0.15 %
		Lead Frame Plating_Metal	0.03 mg	Precious metals	Gold	7440-57-5		0.0002 mg	0.78 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.0285 mg	95.12 %
				Metal	Palladium	7440-05-3		0.0012 mg	4.1 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
		Mold Compound_Epoxy with Silica Filler	0.2226 mg	Chemical	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.0174 mg	7.8002 %
				Chemical	Carbon Black	1333-86-4		0.0011 mg	0.5 %
				Chemical	Proprietary Non Halide			0.0027 mg	1.1999 %
				Chemical	Silica Fused	60676-86-0		0.2003 mg	90 %
				Chemical	Tricresyl phosphate	1330-78-5		0.0011 mg	0.5 %
		Semiconductor Device_Doped Silicon	0.0425 mg	Metalloid	Silicon	7440-21-3		0.0425 mg	100 %
211434-01									
211444	57.22 mg	Resistive Element_Copper Alloy	45.6 mg	Copper and its alloys	Copper	7440-50-8		39.2 mg	85.9649 %
				Metal	Manganese	7439-96-5		5.5 mg	12.0614 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.9 mg	1.9737 %
		Termination_Metal	5.75 mg	Copper and its alloys	Copper	7440-50-8		4 mg	69.5652 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.69 mg	12 %
				Metal	Tin	7440-31-5		1.06 mg	18.4348 %
		Epoxy Resin_Epoxy with Silica Filler	5.7 mg	Chemical	Epoxy Cresol Novolac	29690-82-2		5.02 mg	88.0702 %
				Chemical	Silica Fused	60676-86-0		0.68 mg	11.9298 %
		Marking_Ink	0.17 mg	Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.17 mg	100 %
211444	57.22 mg	Resistive Element_Copper Alloy	45.6 mg	Copper and its alloys	Copper	7440-50-8		39.2 mg	85.9649 %
				Metal	Manganese	7439-96-5		5.5 mg	12.0614 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.9 mg	1.9737 %
		Termination_Metal	5.75 mg	Copper and its alloys	Copper	7440-50-8		4 mg	69.5652 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.69 mg	12 %
				Metal	Tin	7440-31-5		1.06 mg	18.4348 %
		Epoxy Resin_Epoxy with Silica Filler	5.7 mg	Chemical	Epoxy Cresol Novolac	29690-82-2		5.02 mg	88.0702 %
				Chemical	Silica Fused	60676-86-0		0.68 mg	11.9298 %
		Marking_Ink	0.17 mg	Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.17 mg	100 %
211444									
211444	57.22 mg	Overcoat_Epoxy	5.7 mg	Chemical	Epoxy Cresol Novolac	29690-82-2		5.7 mg	100 %
		Resistive Element_Metal	45.6 mg	Aluminum and its alloys	Aluminum	7429-90-5		16.5893 mg	36.38 %
				Copper and its alloys	Copper	7440-50-8		24.9523 mg	54.72 %
				Metal	Manganese	7439-96-5		4.0584 mg	8.9 %
		Marking_Epoxy	0.17 mg	Chemical	Epoxy Cresol Novolac	29690-82-2		0.17 mg	100 %
		Plating_Copper Plating	4 mg	Copper and its alloys	Copper	7440-50-8		4 mg	100 %
		Plating_Nickel Underplating	0.7 mg	Nickel/Nickel Compounds	Nickel	7440-02-0		0.7 mg	100 %
		Plating_Tin Plating	1.05 mg	Metal	Tin	7440-31-5		1.05 mg	100 %
211445	57.22 mg	Resistive Element_Copper Alloy	45.6 mg	Copper and its alloys	Copper	7440-50-8		39.2 mg	85.9649 %
				Metal	Manganese	7439-96-5		5.5 mg	12.0614 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.9 mg	1.9737 %
		Termination_Metal	5.75 mg	Copper and its alloys	Copper	7440-50-8		4 mg	69.5652 %
				Nickel/Nickel Compounds	Nickel	7440-02-0		0.69 mg	12 %
				Metal	Tin	7440-31-5		1.06 mg	18.4348 %
		Epoxy Resin_Epoxy with Silica Filler	5.7 mg	Chemical	Epoxy Cresol Novolac	29690-82-2		5.02 mg	88.0702 %
				Chemical	Silica Fused	60676-86-0		0.68 mg	11.9298 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
		Marking_Ink	0.17 mg	Chemical	Bisphenol A epichlorohydrin polymer	25068-38-6		0.17 mg	100 %
211445									
211445	57.22 mg	Overcoat_Epoxy	5.7 mg	Chemical	Epoxy Cresol Novolac	29690-82-2		5.7 mg	100 %
		Resistive Element_Metal	45.6 mg	Aluminum and its alloys	Aluminum	7429-90-5		16.5893 mg	36.38 %
				Copper and its alloys	Copper	7440-50-8		24.9523 mg	54.72 %
				Metal	Manganese	7439-96-5		4.0584 mg	8.9 %
		Marking_Epoxy	0.17 mg	Chemical	Epoxy Cresol Novolac	29690-82-2		0.17 mg	100 %
		Plating_Copper Plating	4 mg	Copper and its alloys	Copper	7440-50-8		4 mg	100 %
		Plating_Nickel Underplating	0.7 mg	Nickel/Nickel Compounds	Nickel	7440-02-0		0.7 mg	100 %
		Plating_Tin Plating	1.05 mg	Metal	Tin	7440-31-5		1.05 mg	100 %
211591	38.85 mg	Clip_Copper Alloy	5.7 mg	Copper and its alloys	Copper	7440-50-8		5.6886 mg	99.8 %
				Metal	Iron	7439-89-6		0.0086 mg	0.15 %
				Chemical	Phosphorus	7723-14-0		0.0028 mg	0.05 %
		Die_Doped Silicon	1.7 mg	Metalloid	Silicon	7440-21-3		1.7 mg	100 %
		Lead Frame_Copper Alloy	13.9 mg	Copper and its alloys	Copper	7440-50-8		13.8722 mg	99.8 %
				Metal	Iron	7439-89-6		0.0208 mg	0.15 %
				Chemical	Phosphorus	7723-14-0		0.007 mg	0.05 %
		Mold Compound_Epoxy with Silica Filler	8.53 mg	Chemical	Carbon Black	1333-86-4		0.0256 mg	0.3 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		1.6804 mg	19.7 %
				Chemical	Phenolic Resin			0.7677 mg	9 %
				Chemical	Silica Fused	60676-86-0		6.0563 mg	71 %
		Post-Plating_Matte Tin	3.85 mg	Metal	Tin	7440-31-5		3.85 mg	100 %
		Solder Paste_High Temperature Solder	5.17 mg	Lead/Lead Compounds	Lead	7439-92-1	7(a)	4.7823 mg	92.5 %
				Metal	Silver	7440-22-4		0.1293 mg	2.5 %
				Metal	Tin	7440-31-5		0.2585 mg	5 %
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211599	3.783 mg	Die_Doped Silicon	0.05 mg	Metalloid	Silicon	7440-21-3		0.05 mg	100 %
		Lead Frame_Copper Alloy	1.5088 mg	Copper and its alloys	Copper	7440-50-8		1.4745 mg	97.7286 %
				Metal	Iron	7439-89-6		0.0319 mg	2.1116 %
				Chemical	Phosphorus	7723-14-0		0.0004 mg	0.0298 %
				Zinc and its alloys	Zinc	7440-66-6		0.002 mg	0.1299 %
		Lead Frame_Silver	0.0012 mg	Metal	Silver	7440-22-4		0.0012 mg	100 %
		Mold Compound_Epoxy with Silica Filler	2.14 mg	Chemical	Carbon Black	1333-86-4		0.0064 mg	0.3 %
				Chemical	Epoxy Cresol Novolac	29690-82-2		0.3745 mg	17.5 %
				Chemical	Phenolic Novolac	9003-35-4		0.1519 mg	7.1 %
				Chemical	Silica Fused	60676-86-0		1.6071 mg	75.1 %

SubProduct	SubProduct Mass	Material	Material Mass	Substance Category	Substance	CAS	Exemption	Substance Mass	Concentration
		Wire_Copper	0.003 mg	Copper and its alloys	Copper	7440-50-8		0.003 mg	100 %
		Post-Plating_Matte Tin	0.08 mg	Antimony/Antimony Compounds	Antimony	7440-36-0		0 mg	0.0125 %
				Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0 mg	0.025 %
				Metal	Iron	7439-89-6		0 mg	0.0125 %
				Lead/Lead Compounds	Lead	7439-92-1		0 mg	0.0125 %
				Metal	Tin	7440-31-5		0.08 mg	99.9375 %
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